



Product Change Notification

111354 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 111354 - 00

Change Title: Intel® Desktop Board D2500CC and D2500CCE, Boxed and Bulk, PCN 111354-00, Product Material, Change Heat Sink, Add IDT part

Date of Publication: March 08, 2012

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Mar 19, 2012
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Description of Change to the Customer:

1. Reduce the height of the heatsink from 32mm to 25mm to improve compatibility with Mini ITX chassis. The length and width of the heatsink is not changed.
2. Replace the clock chip with an IDT part in order to improve supply availability.

Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BLKD2500CC	915854	G43154-305	G43154-306
BLKD2500CCE	917658	G43156-302	G43156-303

PCN Revision History:

Date of Revision:

March 8, 2012

Revision Number:

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Reason:

Originally Published PCN